

ABSTRACT OF THE DISCLOSURE

An electronic assembly that may include an integrated circuit package that is mounted to a substrate. The
5 assembly may have a thermally conductive phase change material that couples the integrated circuit package to a thermal element. The phase change material may be assembled in a liquid phase to fill any gap between the package and the thermal element. The phase change
10 material may exist in a solid phase during normal operation of the assembly so that the material does not bleed from the package/thermal element interface.